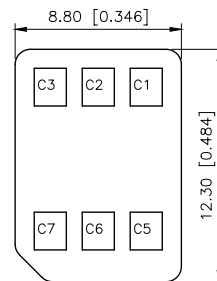
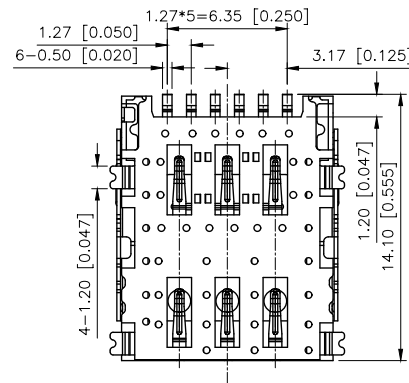
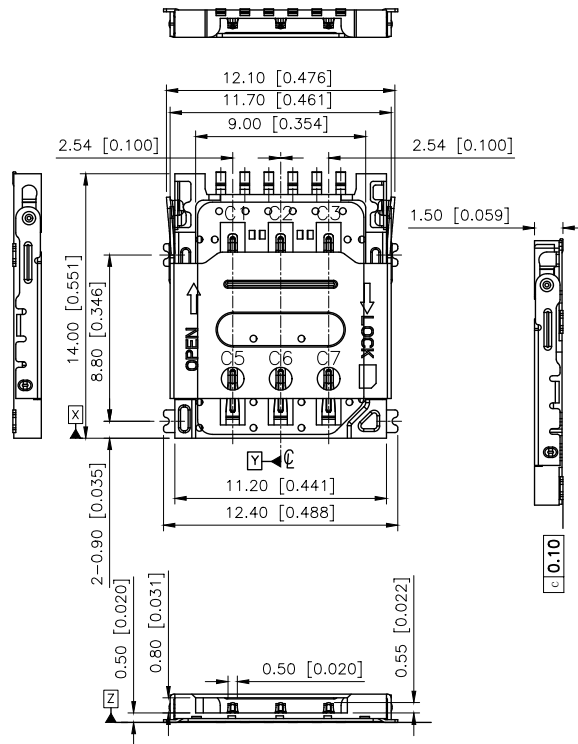
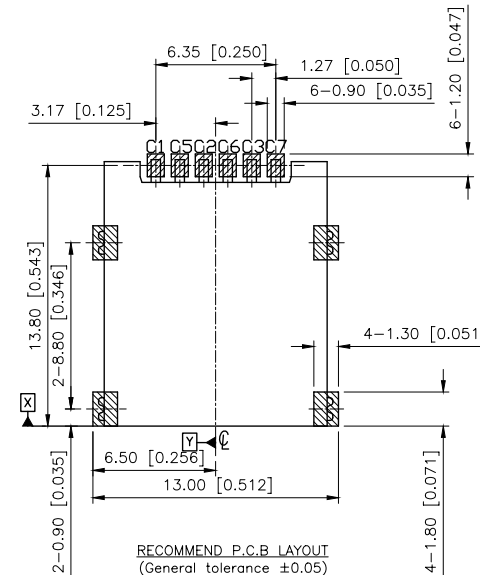
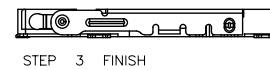
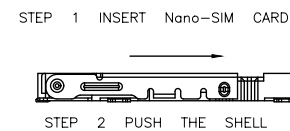
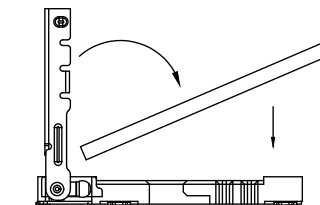


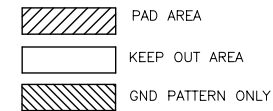
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.08	阿树



NANO SIM CARD



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



NOTE:

1.材料 Material:

- 1-1 胶壳 Housing:High Temperature Thermoplastic.
(LCP S475jColor Black UL94V-0
1-2 触点 Contact:Phosphor Bronze(C5210R-HT=0.15±0.02mm)
1-3 盖 Cover:SUS301-HT=0.20±0.03mm

2.电镀 Plating:

- 接触端子 Contact terminal:
接触电阻 Contact area: Gold 1u" Min.
焊料区 Solder area: Gold 0.8u" Min
底镀 Underplating: Ni overall 50U"Min,

3.规格 Specification:

- 3-1.接触电阻 CONTACT RESISTANCE:50 Milliohms Max
3-2.绝缘电阻 INSULATION RESISTANCE:1.000 Megohms Min.
3-3.绝缘耐压 DIELECTRIC WITHSTANDING VOLTAGE:500V AC FOR 1MINUTE.
3-4.工作温度范围 OPERATION TEMPERATURE RANGE:-25C~+700
3-5.耐用性 DURABILITY:3000 CYCLES

4.Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC

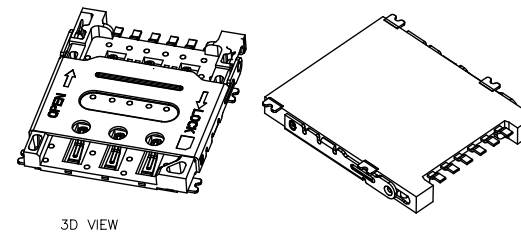
5.Part Must Comply Taisol HFWD-3-1-091 Specification.

6.Recommending A Metal More Than 0.15mm Thick.

Please Confirm Solderability,If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
PIN No.	NAME
C1	Vcc
C2	RST
C3	CLK
C5	GND
C6	Vpp
C7	I/O



3D VIEW

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO-1150
APPROVED		SIZE: A4	DWG NO.: X-XKNANO-1150
XKB INDUSTRIAL PRECISION CO.,LIMITED			SCALE N/A
			PAGE 1/1
			REVISION A1